

Title (en)  
HIGH-TEMPERATURE RESISTANT CRYSTALLIZING SOLDER GLASSES

Title (de)  
HOCHTEMPERATUR-BESTÄNDIGE KRISTALLISIERENDE GLASLOTE

Title (fr)  
VERRES DE SOUDURE À CRISTALLISATION STABLES À HAUTE TEMPÉRATURE

Publication  
**EP 2473454 A2 20120711 (DE)**

Application  
**EP 10760584 A 20100825**

Priority  
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Abstract (en)  
[origin: WO2011023372A2] The invention relates to high-temperature resistant crystallizing solder glasses which contain 20-45 mol% of BaO, 40-60 mol% of SiO<sub>2</sub>, 0-30 mol% of ZnO, 0-10 mol% of Al<sub>2</sub>O<sub>3</sub>, 0-5 mol% of BaF<sub>2</sub>, 0-2 mol% of MgO, 0-2 mol% of CaO, 0-2 mol% of TiO<sub>2</sub>, 0-10 mol% of B<sub>2</sub>O<sub>3</sub>, as well as 0,5-4 mol% of M<sub>2</sub>O<sub>3</sub> (M = Y, La or rare earth elements) and/or 0.5-4 mol% of ZrO<sub>2</sub>, and to the use thereof.

IPC 8 full level  
**C03C 3/068** (2006.01)

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